



Senior Staff Specialist, Process integration

Job description

You will be responsible for outsourced package platform qualification (lead and follower products) and process optimisation at subcons to meet the time-to-market, product quality level, process capability and assembly yield target.

In your new role you will be:

- Responsible for **outsourced package platform qualification** (lead and follower products) and **process optimisation at subcons** to meet the time-to-market, product quality level, process capability and assembly yield target.
- Responsible for **package definition tasks in OSAT segment** in defining project complexity definition with Delta assessment list, project category assessment and Perform project risk assessment with mitigation actions.
- Responsible for **integration of unit processes** till process freeze for assembly and test at subcons which entails creating assembly specification, marking instruction and packing specification for upload into Database
- Apply design rules based on established baseline document as well as specific **equipment and process capability** of specific assembly sites
- Define process and select Bill of Material as needed to meet MSL, reliability level, and other specific package requirements for development and pre-development.
- Responsible for enabling of **new package platform and derivatives packages**, and support of technology and package development at OSAT. This includes new subcon enabling support role.
- As a driver or co-driver for platform related Task force activities

Profile

You are best equipped for this task if you have:

- Master or Bachelor degree in Engineering disciplines.

At a glance

Location: **Bangkok (Thailand)**
Job ID: **351747**
Start date: **as soon as possible**
Entry level: **5+ years**
Type: **Full time**
Contract: **Permanent**

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Job ID: **351747**
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- Minimum **10 years' experience of package development in New product introduction** or process (assembly and test) and 3 years in supporting project management
- Experience in **Wafer level package (WLP), bumping, pre-assembly** such as low K removal, **Laser groove and wafer sawing process** will be a key advantage
- Experience in **Subcon management**
- Strong communication and stakeholder management skills across all levels. Strong analytical skills, ability to deal with conflict and ambiguity.
- Highly motivated with the ability to prioritize and perform under pressure and get team members and stakeholders involved and to motivate them. Ability to collaborate and work as a team with various stakeholders and partners in multi-site/multi-cultural teams

Why Us

Part of your life. Part of tomorrow.

Infineon is a world leader in semiconductor solutions that make life easier, safer, and greener. Our solutions for efficient energy management, smart mobility, and secure, seamless communications link the real and the digital world.

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